

Abstract

5 The present invention relates to a solder paste for the mounting of electronic components and substrates that contains a mixture of oxalic acid, adipic acid, and an amine component as well as to a method for the production thereof. Moreover, the present invention relates to a method for the mounting of an electronic component on a substrate through the use of the solder paste according to the invention as well as to a module that comprises the solder paste according to
10 the invention.

Fig. 2